

ABSTRACT OF THE DISCLOSURE

A thermal enhance semiconductor package with a universal heat spreader mainly comprises a carrier, a semiconductor chip and a universal heat spreader. The semiconductor chip is electrically connected to the carrier in a flip-chip fashion and the universal heat spreader is mounted on the back surface of the semiconductor chip. Therein the universal heat spreader has a plurality of through holes for upgrading the efficiency of heat transmission. Moreover, a heat transmission pin is provided in one of the through holes to increase the areas for heat dissipation so as to enhance the thermal performance of the package.